Safety

- CAUTION! Do Not Touch THE WAFER STAGE when it is HOT!!

Process Restrictions

Material Restrictions
- For removal of thin (< 10 micron) organic films. Thicker films must be cleared through Machine Manager. - Wafers or samples must be clean on back.

Parameter Restrictions
- Process parameters are limited by the Controller.

Scheduling / Sign-up Restrictions
- Scheduling is restricted to a maximum of 2 hour blocks separated by no less than 1 hour.

Requirements (Do Every Time)
- Be sure small chips are "Fenced" with glass microscope slides to prevent sliding off the stage. - Remember to push "PRESS TO RESET" at end of process to shut off the 'Beeper'.

Prohibitions (Never Do)

Never turn the RF power supply tap knob while the power supply is on. Always switch the power supply OFF before turning the tap knob.

Common Problems

<table>
<thead>
<tr>
<th>Problem:</th>
<th>Root Cause:</th>
<th>Solution:</th>
</tr>
</thead>
<tbody>
<tr>
<td>- Machine did not follow expected process parameters.</td>
<td>- Recipe not viewed and checked correctly / &quot;Press To Load Recipe&quot; not pushed (follow instructions carefully).</td>
<td>- Push - &quot;Press to Load Recipe&quot;</td>
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Other Comments or Cautions
- Care must be used not to scratch the aluminum stage with metal tools. - Care must be used when moving the S.S. pins not to jam them.